

ABSTRACT

B3 A substrate cleaning system for cleaning wafers using a sheet-type wet cleaning treatment. The system has a sealable system body, a loading/unloading booth having a substrate carry-in section in which a plurality of substrates are stocked to be carried in before a cleaning treatment is applied to them and a substrate carry-out section in which a plurality of substrates are stocked to be carried out after the cleaning treatment is applied, a processing booth provided with at least one sheet-type substrate cleaning chamber in which the cleaning treatment can be applied to a plurality of substrates by a plurality of cleaning solutions, and a robot booth provided with a transport robot for transporting the substrates one by one between the processing booth and the loading/unloading booth, the respective booths having partition walls.